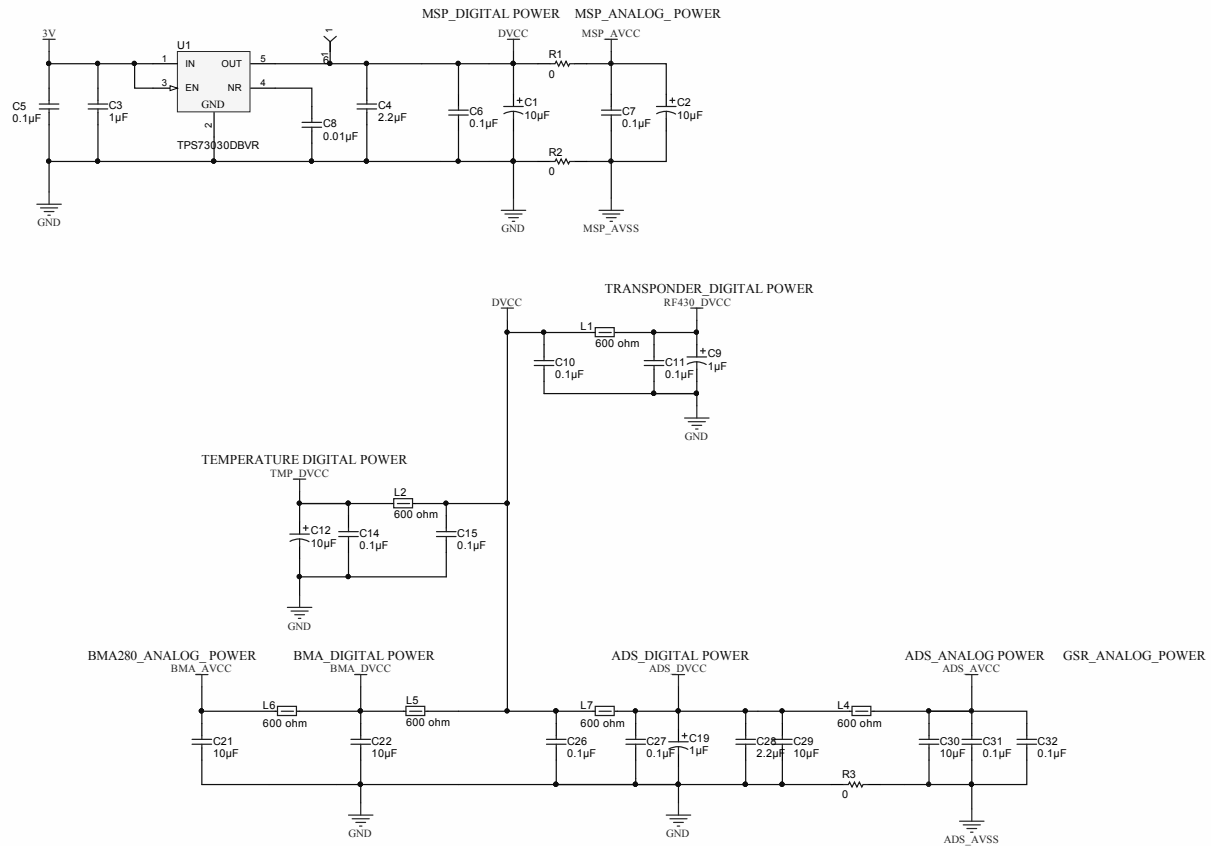


Power Distribution



1

2

3

4

5

6

7

8

A

A

B

B

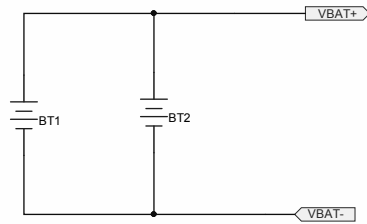
C

C

D

D

Current Protection Subcircuit



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Number: TIDM-BIOSIGNMONITOR		Mod. Date: 1/7/2016	
Designed for: Public Release			
Project: Multi-Parameter Bio-signal monitor			
Sheet Title: Battery Subcircuit		Sheet: 3 of 12	
Size: A3		Schematic: 870PRJ BasePN Rev. E2	
Assembly Variant: [No Variations]			
File: MPBSM_Battery_SchDoc			
Contact: http://www.ti.com/support			



<http://www.ti.com>
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1

2

3

4

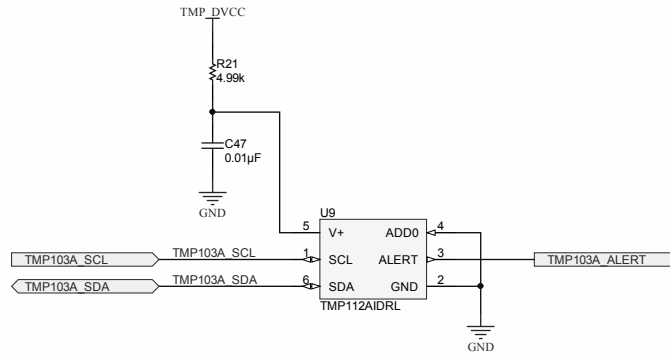
5

6

7

8

Local Temperature Sensor

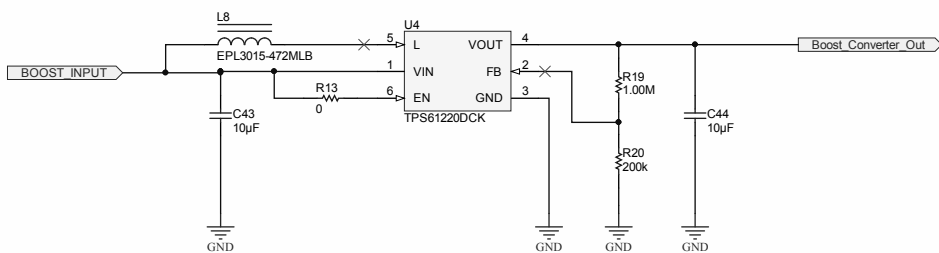


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Number: TIDM-BIOSIGNMONITOR	Mod. Date: 1/7/2016
Designed for: Public Release	
Project: Multi-Parameter Bio-signal monitor	
Sheet Title: MPBSM Temperature Subcircuit	Sheet: 11 of 12
Size: A3	Schematic: 870PRJ BasePN Rev. E2
Assembly Variant: [No Variations]	
File: MPBSM_Temperature.SchDoc	
Contact: http://www.ti.com/support	



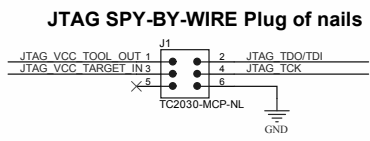
Boost Converter



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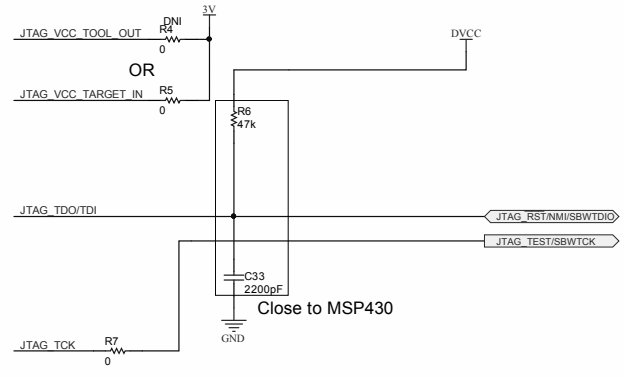
Number: TIDM-BIOSIGNMONITOR		Mod. Date: 1/7/2016	
Designed for: Public Release			
Project: Multi-Parameter Bio-Signal monitor		Sheet: 4 of 12	
Sheet Title: Boost Converter Subcircuit		Rev: E2	
Size: A3		Schematic: 870PR.J BasePN	
Assembly Variant: [No Variations]			
File: MPB5M_BoostConverter.SchDoc			
Contact: http://www.ti.com/support			



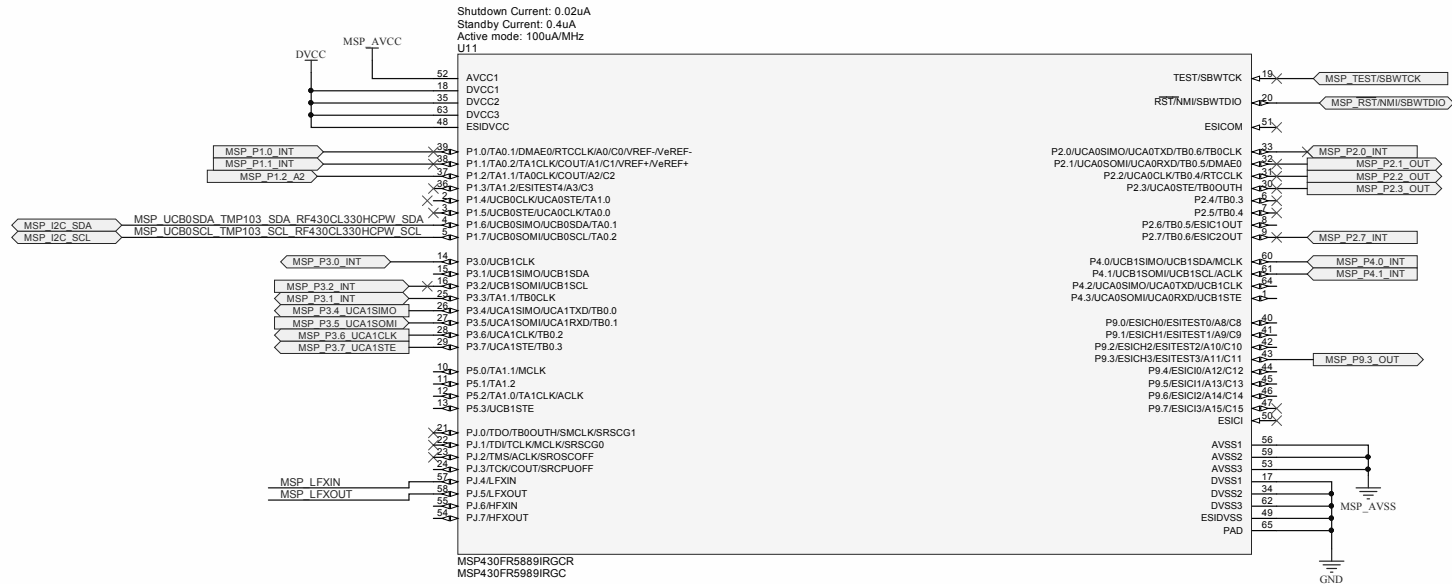
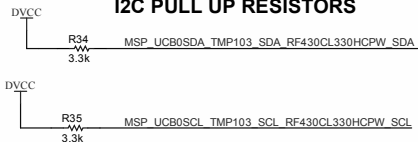


JTAG SPY-BY-WIRE FILTERING

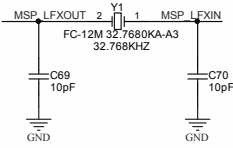
Close to MSP430

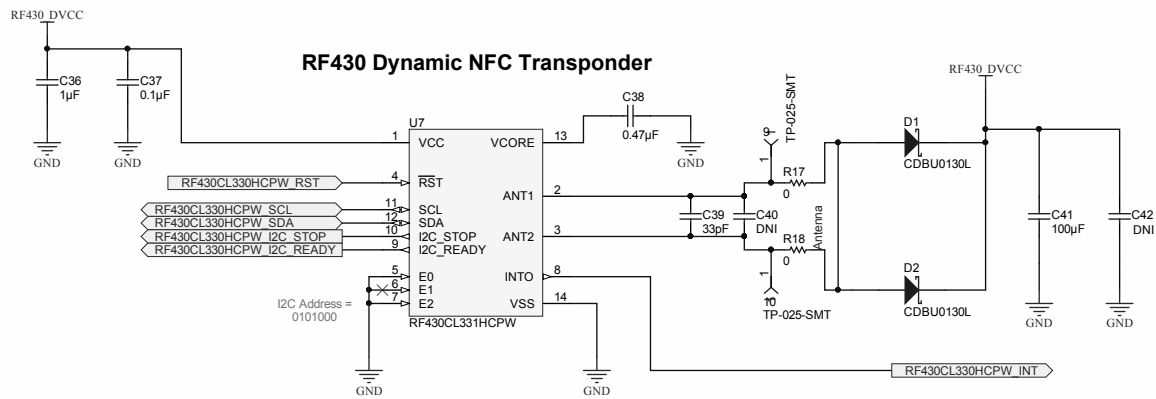


I2C PULL UP RESISTORS



Close to MSP430



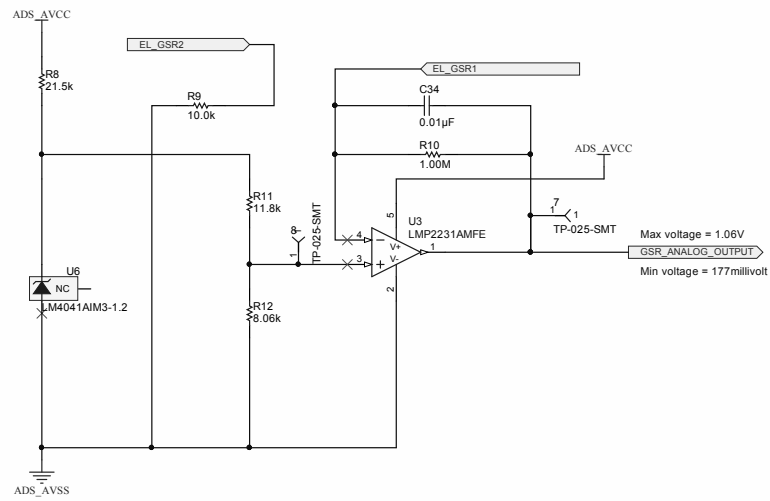


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Number: TIDM-BIOSIGNMONITOR	Mod. Date: 1/7/2016
Designed for: Public Release	
Project: Multi-Parameter Bio-signal monitor	
Sheet Title: NFC Transponder Subcircuit	Sheet 9 of 12
Size: A3	Schematic: 870PRJ_BasePN Rev. E2
Assembly Variant: [No Variations]	
File: MPBSM_NFC_Trans_SchDoc	
Contact: http://www.ti.com/support	



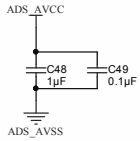
Galvanic Skin Response Subcircuit



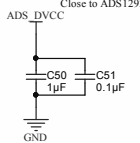
Texas Instruments and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. Texas Instruments and/or its licensors warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. Texas Instruments and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your applic		Number: TIDM-BIOSIGNMONITOR	Designed for Public Release	Mod. Date: 1/7/2016
		Rev: E2	Project Title: Multi-Parameter Bio-signal monitor	
		Not in version control	Sheet Title: MPBSM GSR Subcircuit	
		Drawn By:	Assembly Variant/No Variations	Sheet 8 of 12
		Engineer: Ricky Zepeda	File: MPBSM_GSR_SchDoc	Size: B
			Contact: http://www.ti.com/support	http://www.ti.com



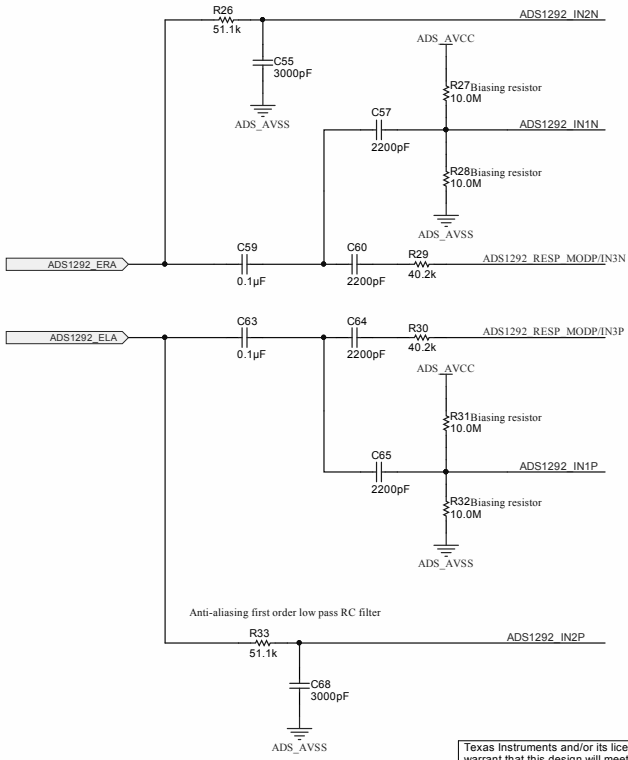
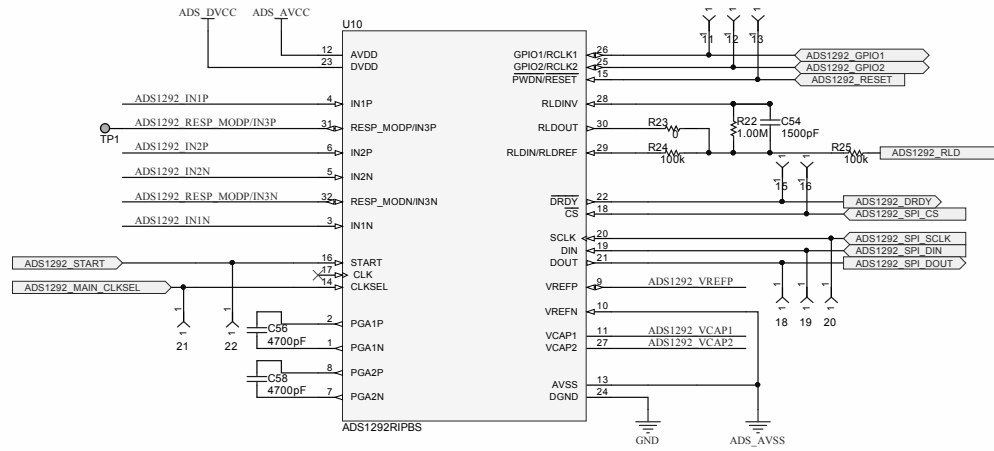
Decoupling Capacitors
Close to ADS1292R



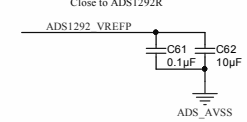
Decoupling Capacitors
Close to ADS1292R



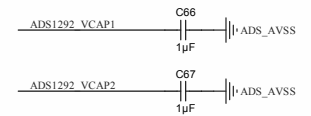
Two-lead ECG with Respiration Detection subcircuit



Decoupling Capacitors
Close to ADS1292R

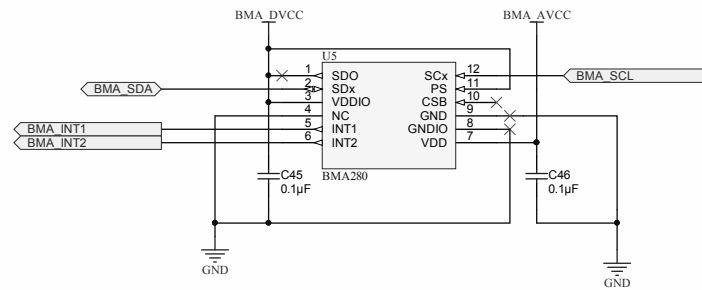


Decoupling Capacitors
Close to ADS1292R



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Number: TIDM-BIOSIGNMONITOR	Designed for Public Release	Mod. Date: 1/7/2016	 TEXAS INSTRUMENTS http://www.ti.com © Texas Instruments 2014
Project Title: Multi-Parameter Bio-signal monitor	Rev: E2	Sheet Title: MPBISM ECG subcircuit	
Rev: Not in version control	Assembly Variant/No Variations	Sheet: 7 of 12	
Drawn By: Engineer: Ricky Zepeda	File: MPBISM_ECG_SchDoc	Size: B	
Contact: http://www.ti.com/support			



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Number: TIDM-BIOSIGNMONITOR		Mod. Date: 1/7/2016	
Designed for: Public Release			
Project: Multi-Parameter Bio-signal monitor			
Sheet Title: MPBSM Triaxial Subcircuit		Sheet: 10 of 12	
Size: A3		Schematic: 870PRJ BasePN Rev. E2	
Assembly Variant: [No Variations]			
File: MPBSM_BMA280_SchDot			
Contact: http://www.ti.com/support			



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